

# SSC8022GS6

#### N-Channel Enhancement Mode MOSFET

#### > Features

V <sub>DS</sub>	V <sub>GS</sub>	R <sub>DS(ON)</sub> Typ.	I <sub>D</sub>
20V	+12V	35mΩ@4.5V	3.5A
201		45mΩ@2.5V	0.07 (

# Description

This device is produced with high cell density DMOS trench technology, which is especially used to minimize on-state resistance. This device particularly applications suits low voltage such as portable equipment, power management and other battery powered circuits, and low in-line power dissipation are needed in a very small outline surface mount package. Excellent thermal and electrical capabilities.

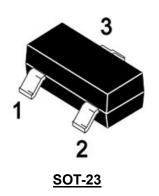
## Applications

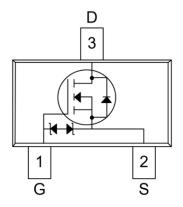
- Load Switch
- Portable Devices
- DCDC Conversion

## Ordering Information

Device	Package	Shipping		
SSC8022GS6	SOT-23	3000/Reel		

# Pin configuration





Pin Configuration (Top View)





# Absolute Maximum Ratings (T<sub>A</sub>=25<sup>°</sup>C unless otherwise noted)

Symbol	Parameter	Ratings	Unit
V <sub>DSS</sub>	Drain-to-Source Voltage	20	V
V <sub>GSS</sub>	Gate-to-Source Voltage	±12	V
I <sub>D</sub>	Continuous Drain Current <sup>a</sup>	3.5	Α
I <sub>DM</sub>	Pulsed Drain Current <sup>b</sup>	10	Α
P <sub>D</sub>	Power Dissipation <sup>c</sup>	0.9	W
P <sub>DSM</sub>	Power Dissipation <sup>a</sup>	0.5	W
TJ	Operation junction temperature	-55~150	$^{\circ}$
T <sub>STG</sub>	Storage temperature range	-55~150	$^{\circ}$

# ➤ Thermal Resistance Ratings (T<sub>A</sub>=25°C unless otherwise noted)

Symbol	Parameter	Typical	Maximum	Unit
Reja	Junction-to-Ambient Thermal Resistance a		260	°C AM
R <sub>θJC</sub>	Junction-to-Case Thermal Resistance		150	°C/W

#### Note:

- a. The value of R<sub>θJA</sub> is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz.copper, in a still air environment with T<sub>A</sub>=25 °C. The value in any given application depends on the user is specific board design. The power dissipation is based on the t≤10s thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation P<sub>D</sub> is based on T<sub>J(MAX)</sub>=150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.

SSC-V2.2 www.sscsemi.com Analog Future



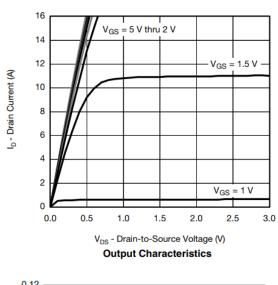


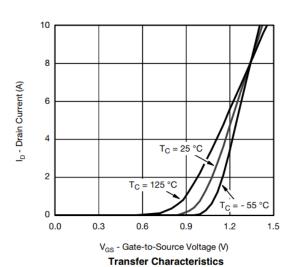
# $\succ$ Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

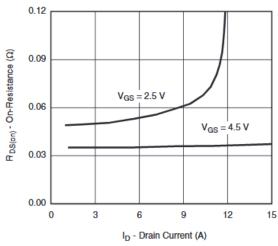
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250µA	20			V	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 250uA$	0.4	0.7	1.2	V	
Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 3.5A		35	50	Ω	
Diam-Source On-Nesistance		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 3A		45	65	12	
Zero Gate Voltage Drain Current	loss	V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V			1	μA	
Gate-Source Leak Current	Igss	$V_{GS} = \pm 12V, V_{DS} = 0V$			±100	nA	
Transconductance	G <sub>FS</sub>	V <sub>DS</sub> = 5V, I <sub>D</sub> =3.5A		8	13	S	
Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> = 1.1A		0.8	1.15	V	
Input Capacitance	Ciss	V <sub>DS</sub> = 10V,		450			
Output Capacitance	Coss	V <sub>DS</sub> = 10V, V <sub>GS</sub> = 0V, f = 1MHz		70		pF	
Reverse Transfer Capacitance	C <sub>RSS</sub>	VGS - UV, I - IIVII IZ		43			
Turn-on Delay Time T <sub>D(ON)</sub>				6			
Rise Time	Tr	$V_{GS} = 4.5V, V_{DS} = 5V,$		9			
Turn-off Delay Time	$T_{D(OFF)}$	$R_G = 6\Omega$ , $I_D = 3.5A$ ,		18		ns	
Fall Time	Tf			12			
Total Gate Charge	Q <sub>G</sub>			11			
Gate Source Charge	Q <sub>GS</sub>	VGS=4.5V, VDS=10V, ID=3A		1.1		nC	
Gate Drain Charge	Q <sub>GD</sub>	V 50 10V, 15-0A		3.3			

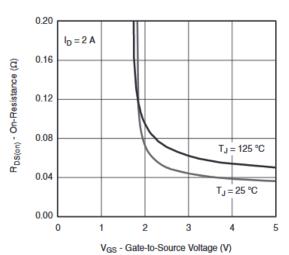


# ➤ Typical Performance Characteristics (T<sub>A</sub>=25°C unless otherwise noted)



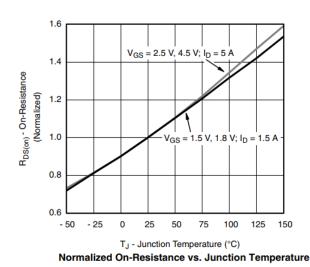


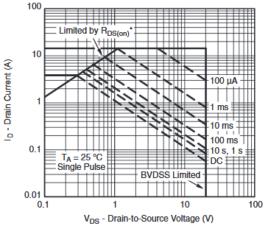




On-Resistance vs. Drain Current and Gate Voltage

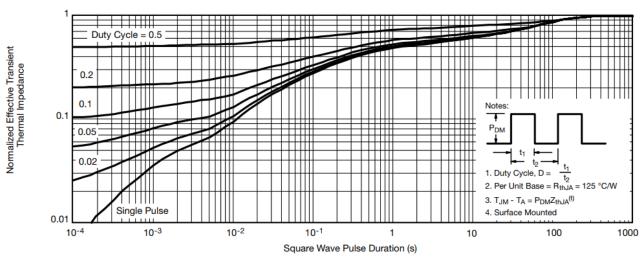






\* V<sub>GS</sub> > minimum V<sub>GS</sub> at which R<sub>DS(on)</sub> is specified Safe Operating Area, Junction-to-Ambient

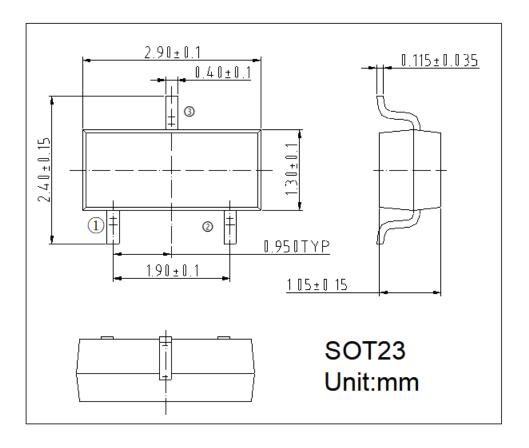




Normalized Thermal Transient Impedance, Junction-to-Ambient

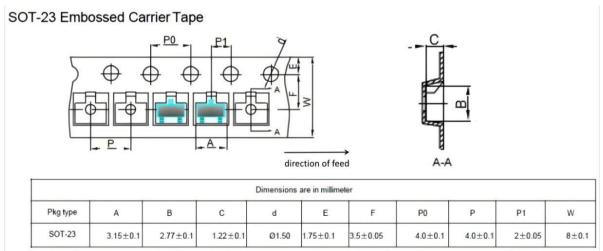


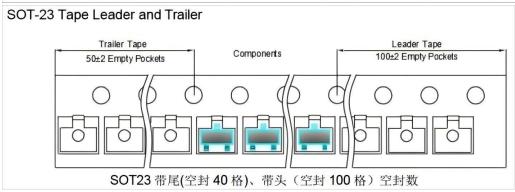
# Package Information



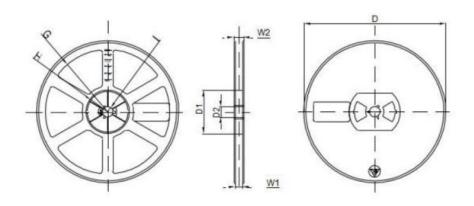


# ➢ SOT-23 Tape and reel





### SOT-23 Reel



			Dimensio	ns are in millime	ter			
Reel Option	D	D1	D2	G	Н	1	W1	W2
7"Dia	Ø178.00	Ø54±0.2	13.3±0.2	R79.00	R26.00	R6.50±0.2	9±0.5	12±0.5



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